



YEA SHIN TECHNOLOGY CO., LTD

YS0854VBB

Dual N-Channel Enhancement MOSFET

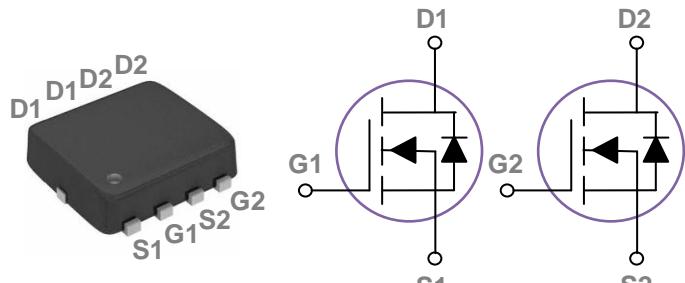
VDS= 100V, ID= 5.1A



Features

- 100V, 5.1A, $R_{DS(ON)} = 3 \text{ m}\Omega$ @ $V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

PPAK3x3 Dual Pin Configuration



Applications

- Networking
- Load switch
- LED applications

Absolute Maximum Rating $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_A=25^\circ\text{C}$)	1.6	A
	Drain Current – Continuous ($T_A=70^\circ\text{C}$)	1.28	A
	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	5.1	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	3.2	A
I_{DM}	Drain Current – Pulsed ¹	20.4	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	20.1	W
	Power Dissipation – Derate above 25°C	0.16	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	6.2	$^\circ\text{C}/\text{W}$

DEVICE CHARACTERISTICS

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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	100	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $\text{I}_D=1\text{mA}$	---	0.09	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=100\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=85^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$\text{R}_{\text{DS(ON)}}$	Static Drain-source On-Resistance	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=3\text{A}$	---	290	350	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=2\text{A}$	---	300	360	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	1.2	1.8	2.5	V
			---	-5	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=10\text{V}$, $\text{I}_D=1\text{A}$	---	2.3	---	S

Dynamic and Switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$\text{V}_{\text{DS}}=50\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=1\text{A}$	---	9	18	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	2.3	4.6	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	1.1	2.5	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time ^{2,3}	$\text{V}_{\text{DD}}=50\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_G=3.3\Omega$, $\text{I}_D=1\text{A}$	---	5.2	10	ns
T_r	Rise Time ^{2,3}		---	6.8	12	
$\text{T}_{\text{d(off)}}$	Turn-On Delay Time ^{2,3}		---	14.5	28	
T_f	Fall Time ^{2,3}		---	2.1	5	
C_{iss}	Input Capacitance		---	492	800	pF
C_{oss}	Output Capacitance	$\text{V}_{\text{DS}}=25\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	27	50	
C_{rss}	Reverse Transfer Capacitance		---	15	25	
R_g	Gate Resistance	$\text{V}_{\text{GS}}=0\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$, $f=1\text{MHz}$	---	2.8	5.6	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	5.1	A
I_{SM}	Pulsed Source Current		---	---	10.2	A
V_{SD}	Diode Forward Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

DEVICE CHARACTERISTICS

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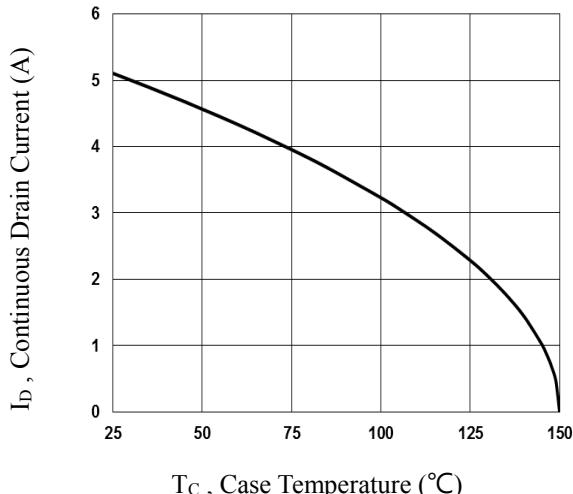


Fig.1 Continuous Drain Current vs. T_c

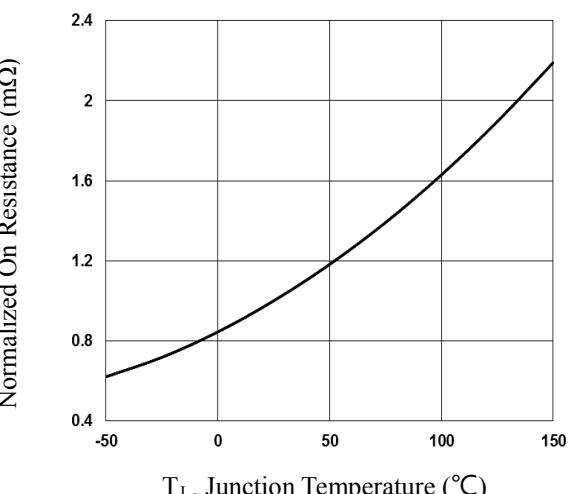


Fig.2 Normalized RDSON vs. T_j

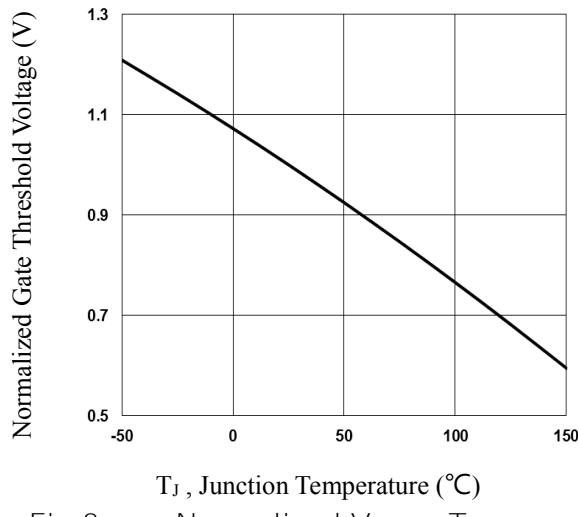


Fig.3 Normalized V_{th} vs. T_j

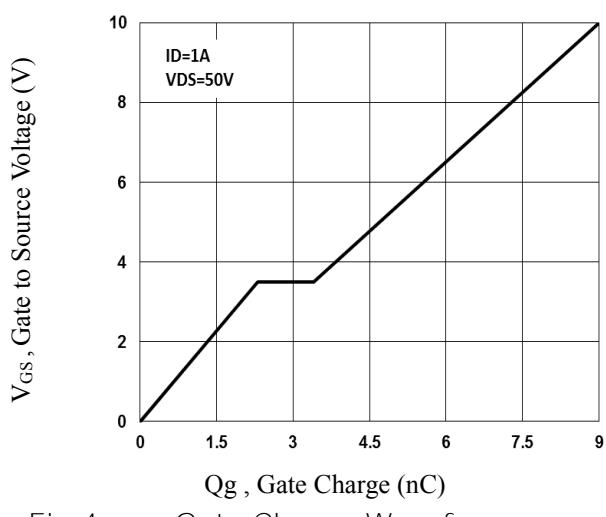


Fig.4 Gate Charge Waveform

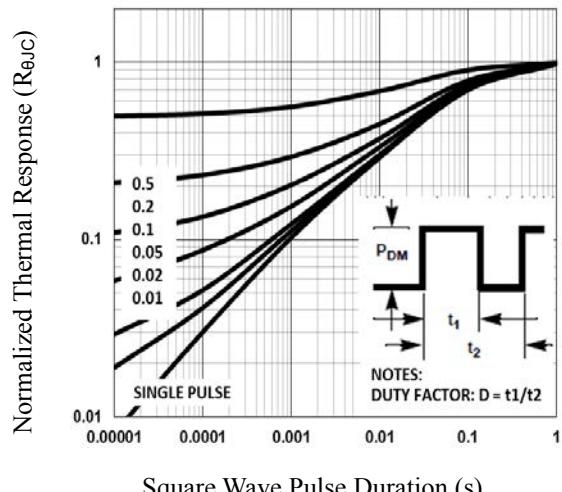


Fig.5 Normalized Transient Impedance

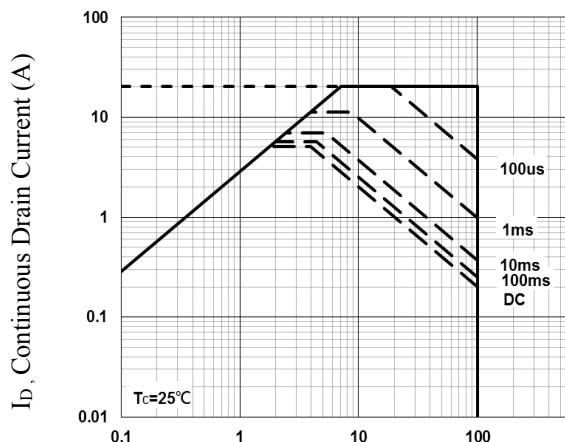


Fig.6 Maximum Safe Operation Area

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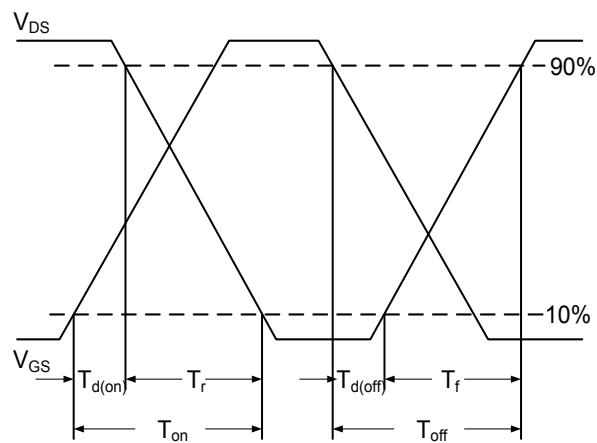


Fig.7 Switching Time Waveform

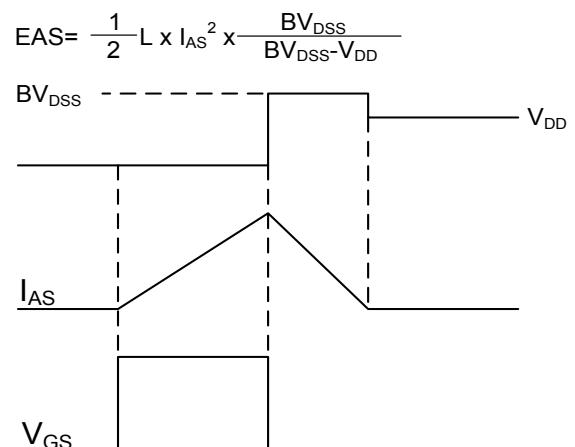
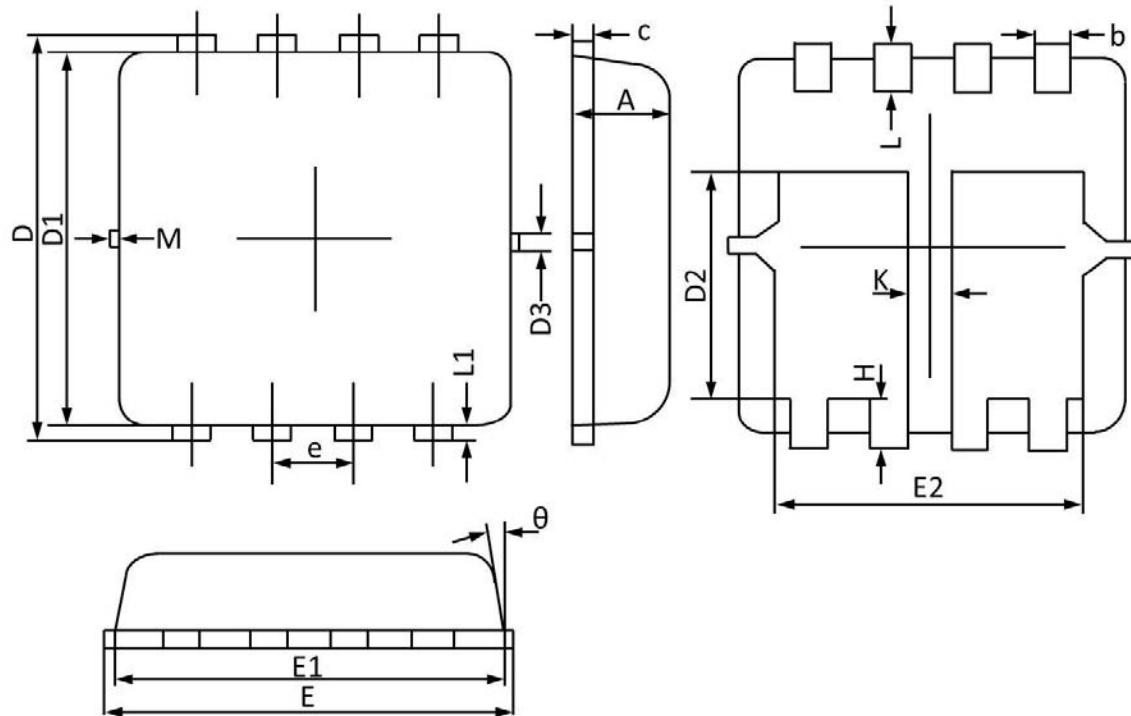


Fig.8 EAS Waveform

PACKAGE OUTLINE & DIMENSIONS

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PPAK3x3 Dual PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 REF		0.005 REF	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 REF		0.005 REF	
K	0.300 REF		0.012 REF	
θ	0°	12°	0°	12°
M	0.150 REF		0.006 REF	